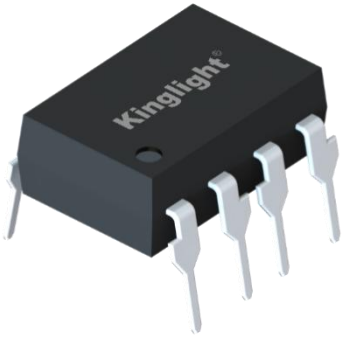
Kinglight®晶台

KL840A,KL860A

DIP8 2-CHANNEL TYPE FORM A SSR

DIP8 双通道FORM A固态继电器



1. 产品特点 Product features

- 结构紧凑型8引脚DIP Compact 8-pin DIP size
- 可应用于2 Form A也可应用于两个独立的1 Form A
  Applicable for 2 Form A use as well as two independent 1 Form A use
- 控制低电平模拟信号 Controls low-level analog signals
- 高灵敏度和高响应速度 High sensitivity and high speed response
- 低电平关断状态漏电流最大值1uA Low-level off state leakage current of max. 1uA
- 工作温度范围(-40°C 至 85°C) Wide operating temperature range of -40°C to 85°C
- 无卤素 (溴<900ppm, 氯<900ppm, 溴+氯<1500ppm)
  Halogens free (Br < 900ppm, Cl < 900ppm, Br+Cl < 1500ppm)
- 输入与输出间高隔离电压 (Viso=5000 V rms)
  High isolation voltage between inputs and output (Viso=5000 V rms)
- 符合欧盟REACH法规 Compliance with EU REACH
- 无Pb且符合ROHS标准 Pb free and RoHS compliant

2. 产品描述 Product Description

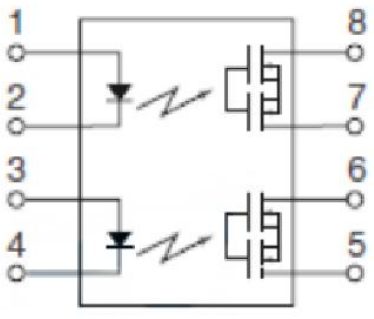
- KL840A 和 KL860A 是固态继电器，它们在发光侧（输入端）装有一个 AlGaAs 红外线 LED，通过光学耦合连接到高压输出检测器电路。检测器由光电二极管阵列和输出侧的 MOSFET 组成。双通道配置相当于 1 form A EMR。
  The KL840A and KL860A are solid state relays containing an AlGaAs infrared LEDs on the light emitting side (input side) optically coupled to a high voltage output detector circuit. The detector consists of a photovoltaic diode array and MOSFETs on the output side. The dual channel configuration is equivalent to 1 form A EMR.
- 它们采用 8 引脚 DIP 封装，并提供表面贴装 SMD 选项。
  They are packaged in 8 pin DIP and available in surface mount SMD option.

3. 产品应用 Product Applications

- 高速检测设备 High-speed inspection machines
- 电话设备 Telephones equipment
- 电脑 Computer

4. 功能图 Functional Diagram

Schematic



引脚配置 Pin Configuration
1,3. LED阳极 LED Anode
2,4. LED阴极 LED Cathode
8,7,6,5. 金属-氧化物半导体场效应晶体管 MOSFET

5. 光电特性 Electrical-Optical characteristics

• 最大限度额定值(温度=25℃) Absolute Maximum Ratings(T_A=25℃)

参数 Parameter		符号 Symbol	额定值 Rated Value		单位 Unit
			KL840A	KL860A	
输入 Input	正向电流 Forward current	I_F	50		mA
	反向电压 Reverse voltage	V_R	5		V
	峰值正向电流 (1*) Peak Forward Current	I_{FP}	1		A
	功耗 Power dissipation (T_A = 25°C)	P_{IN}	75		mW
输出 Output	击穿电压 (2*) Break Down Voltage	V_L	400	600	V
	持续负载电流 Continuous Load Current	I_L	120	50	mA
	脉冲负载电流 (3*) Pulse Load Current	I_{Lpeak}	0.3	0.15	A
	功耗 Power Dissipation	P_{out}	800		mW
总功耗 Total Power Dissipation		P_T	850		mW
隔离电压 (4*) Isolation Voltage		V_{iso}	5000		V rms
工作温度 Operating temperature		T_{OPR}	-40 to +85		℃
储存温度 Storage temperature		T_{STG}	-40 to +125		℃
焊接温度 (5*) Soldering temperature		T_{SOL}	260		℃

附注 (Notes):

1* f =100Hz，占空比 = 0.1% f =100Hz, Duty Cycle = 0.1%

2* 直流和交流峰值 Indicate the DC and peak AC values

3* A 连通：100 ms（1 次），V_L = 直流或交流峰值 A connection: 100 ms (1 shot), V_L = DC or peak AC

4* 交流电源1分钟内, 相对湿度在40~60%RH环境下, 隔离电压测试时, 1&2脚短接在一起, 3&4脚短接在一起

AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1&2 are shorted together, and pins 3,&4 are shorted together.

5* 焊接时间为10秒 Soldering time is 10 seconds

6. 电气特性(Ta=25℃,除非另有规定)

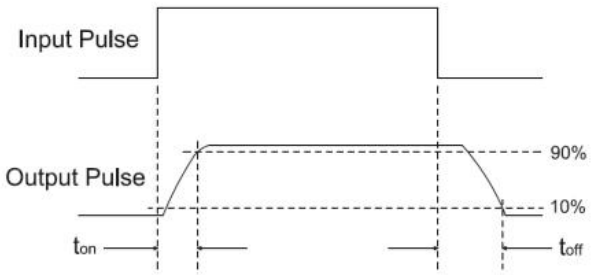
Electrical Characteristics(Ta=25℃ unless specified otherwise)

参数 Parameter			符号 Symbol	最小值 Min.	规格值 Typ.	最大值 Max.	单位 Unit	条件 Condition
输入 In put	正向电压 Forward voltage		V_F	-	1.18	1.5	V	I_F=10mA
	反向电流 Reverse current		I_R	-	-	1	uA	V_R=5V
输出 Out put	关闭状态泄漏电流 Off State leakage Current		I_{leak}	-	-	1	uA	I_F = 0mA, V_L = Max
	导通电阻 On Resistance	KL840A	$R_{d(ON)}$	-	20	30	Ω	I_F = 10mA, I_L = Max. t = 1s
		KL860A		-	40	70		
	输出电容 Out put Capacitance	KL840A	C_{out}	-	45	-	pF	V_L = 0V, f = 1MHz
		KL860A		-	30	-		

• 传输特性 Transfer Characteristics

参数 Parameter		符号 Symbol	最小值 Min.	规格值 Typ.*	最大值 Max.	单位 Unit	条件 Condition
LED 打开电流 LED turn on Current	KL840A	$I_{F(on)}$	-	3	5	mA	I_L = Max.
	KL860A						
LED 关闭电流 LED turn off Current	KL840A	$I_{F(off)}$	0.4	3	-	mA	I_L = Max.
	KL860A						
打开时间 Turn On Time	KL840A	T_{on}	-	0.4	3	ms	I_F = 10 mA, I_L = Max. R_L = 200Ω ,
	KL860A		-	1.4	3		
关闭时间 Turn Off Time	KL840A	T_{off}	-	0.05	0.5	ms	
	KL860A		-	0.05	0.5		
隔离电阻 Isolation Resistance		R_{I-O}	5×10^{10}	-	-	Ω	V_{I-O} = 500V DC
隔离电容 Isolation Capacitance		C_{I-O}	1.5	-	-	pF	V = 0V, f = 1MHz

打开/关闭时间 Turn on/Turn off Time



7. 特性曲线 Characteristic Curves

图1. 负载电流 vs 环境温度的关系

Figure 1. Load Current vs Ambient Temperature

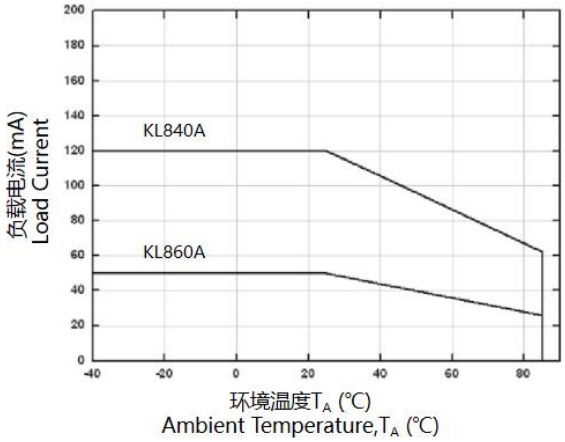


图2. 导通电阻 vs 环境温度的关系

Figure 2. On Resistance vs Ambient Temperature

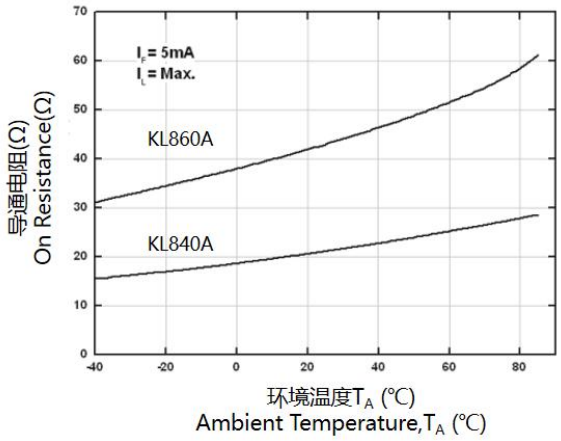


图3. 响应时间 vs 环境温度的关系

Figure 3. Switching Time vs Ambient Temperature

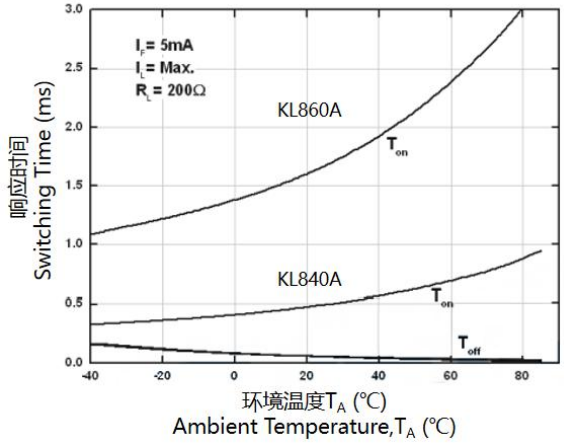


图4. 开启时间 vs LED正向电流的关系

Figure 4. Turn-on Time vs LED Forward Current

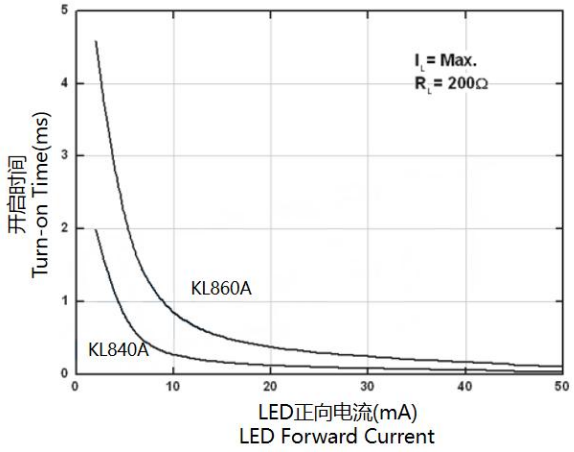


图5. 关闭时间 vs LED正向电流的关系

Figure 5. Turn-off Time vs LED Forward Current

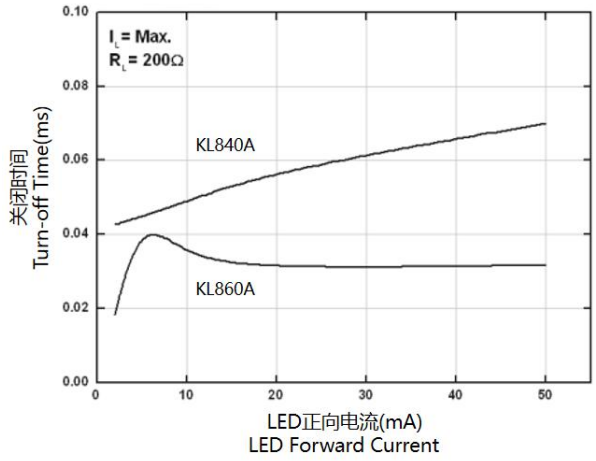


图6. LED工作电流 vs 环境温度的关系

Figure 6. LED operate on Current vs Ambient Temperature

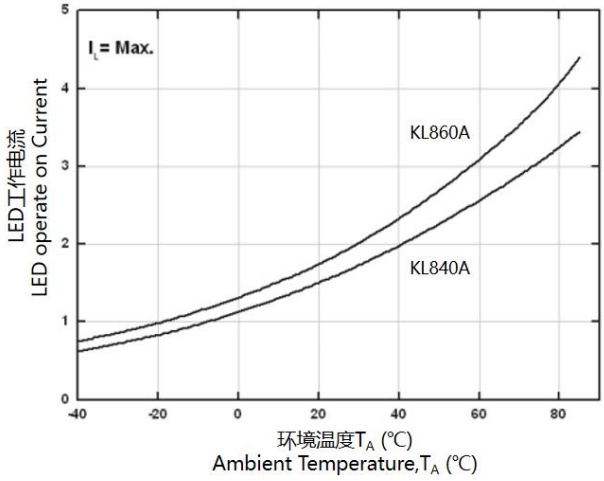


图7. LED关闭电流 vs 环境温度的关系
Figure 7 LED turn off Current vs Ambient Temperature

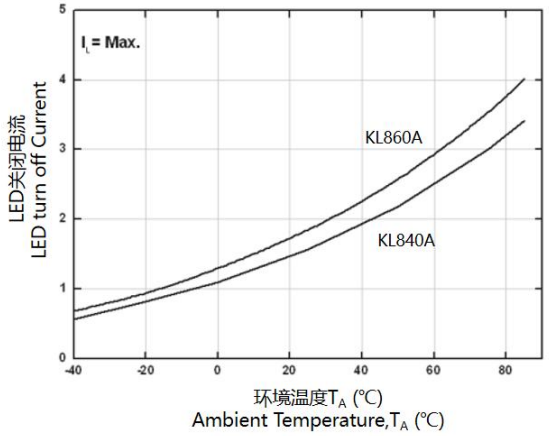


图8. LED下降电压 vs 环境温度的关系
Figure 8. LED Dropout Voltage vs Ambient Temperature

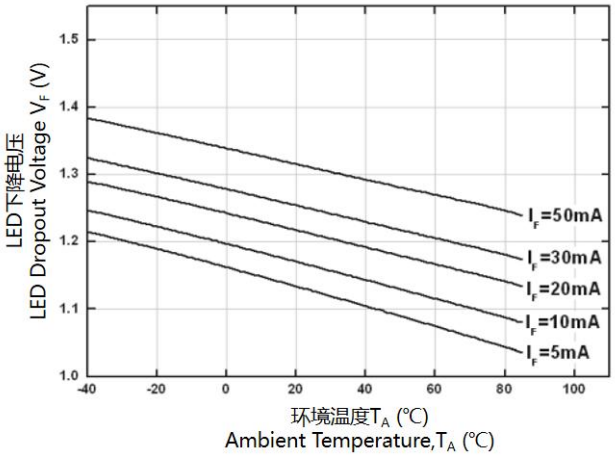


图9. 负载电流 vs 负载电压的关系
Figure 9. Load Current vs Load Voltage

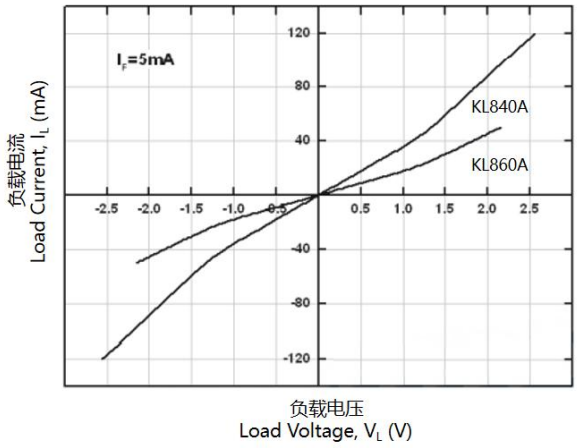


图10. 断态漏电流 vs 负载电压的关系
Figure 10 Off State Leakage Current vs Load Voltage

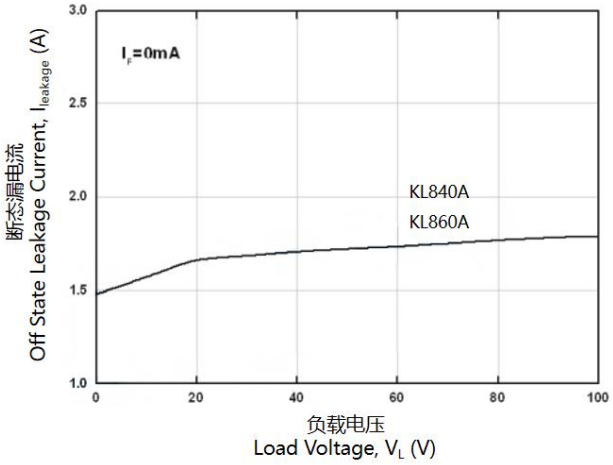
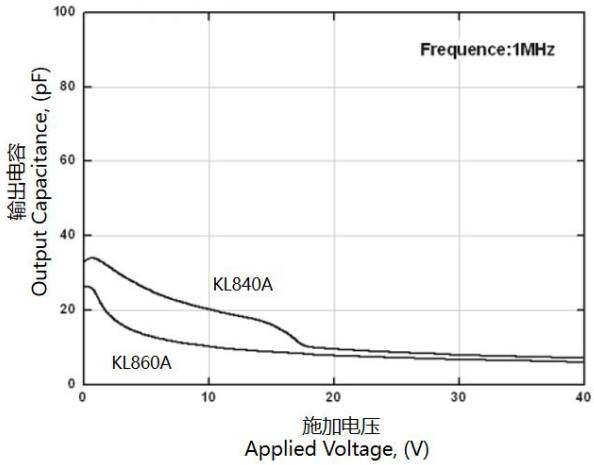


图11. 输出电容 vs 施加电压
Figure 11. Output Capacitance vs Applied Voltage



8. 订单信息 Order Information

• 材料编号 Part Number

KL8XXAY-Z-V

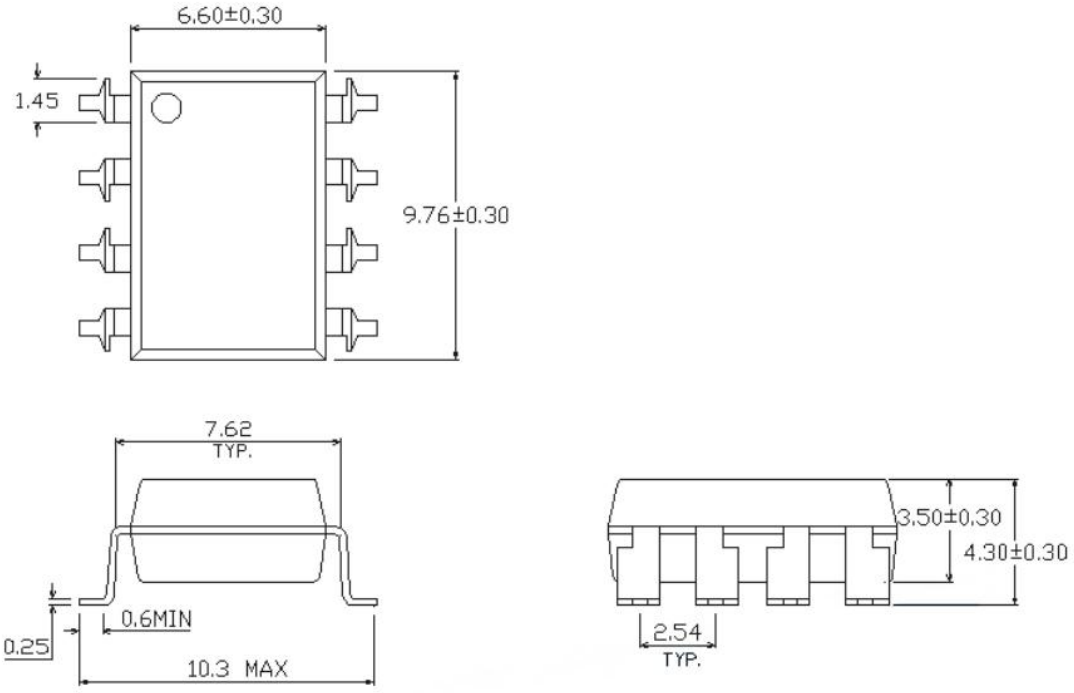
附注(Notes):

XX =零件编号(40或60) Part No. (40 or 60)
Y = 引脚形式选项(S1或无)
Lead form option (S1 or none)
Z = 料带和卷轴选项(TA、TB、TU、TD or none)
Tape and reel option (TA, TB, TU, TD或无)
V = 表示VDE标识(客户指定镭射字符才加"V")
VDE (Only add "V" to laser characters specified by the customer)

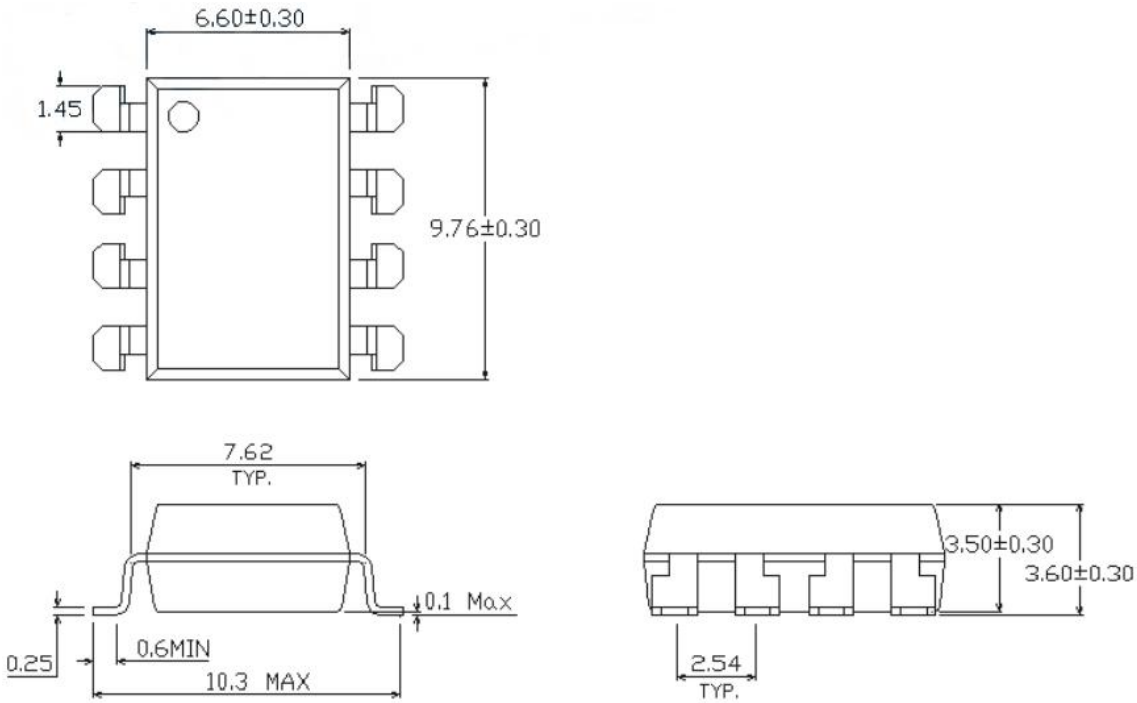
选项 Option	描述 Description	包装数量 Packing quantity
无 None	标准 DIP-8 Standard DIP-8	每管45pcs 45 units per tube
S1-TA	表面贴装引线形式(低剖面)+TA载带和卷轴选项 Surface mount lead form (low profile) + TA tape & reel option	每卷1000pcs 1000 units per reel
S1-TB	表面贴装引线形式(低剖面)+TB载带和卷轴选项 Surface mount lead form (low profile) + TB tape & reel option	每卷1000pcs 1000 units per reel

9. 封装尺寸(单位:毫米) Package Drawing(Unit:mm)

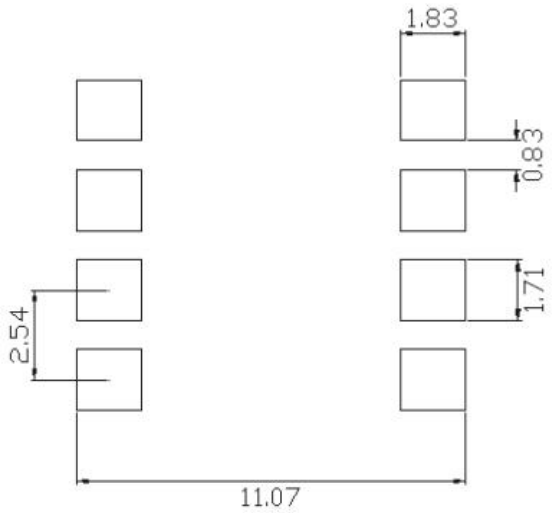
• 标准DIP型号 Standard DIP Type



• 选择S1型号 Option S1 Type



• 表面贴装引线框架 推荐焊盘布局 Recommended pad layout for surface mount leadform

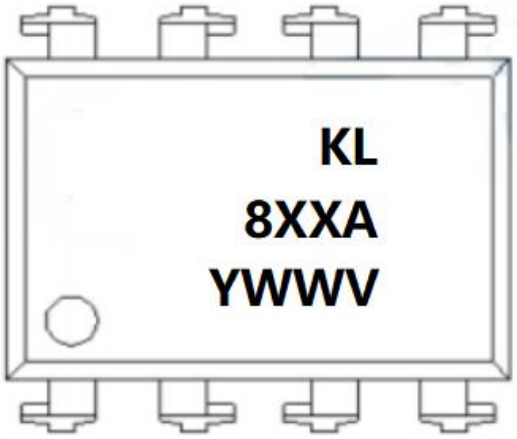


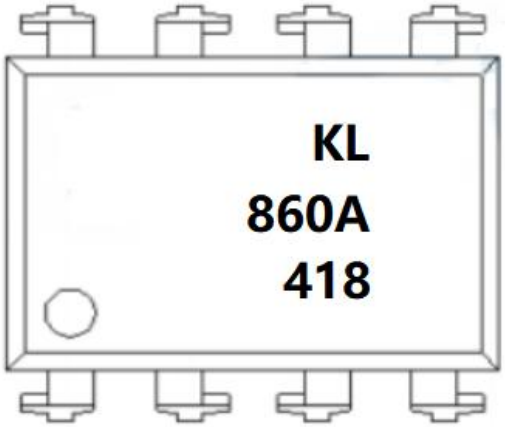
附注(Notes):

a. 建议焊盘尺寸仅供参考 Suggested pad dimension is just for reference only

b. 请根据个人需要修改焊盘尺寸 Please modify the pad dimension based on individual need

10.设备标记 Device marking





(范本参考 Template reference)

附注(Notes):

KL = 表示晶台光电有限公司 Denotes KingLight

8XXA = 表示材料部件号 Denotes Device Part Number
XX表示零件编号(40或60) Part No. (40 or 60)

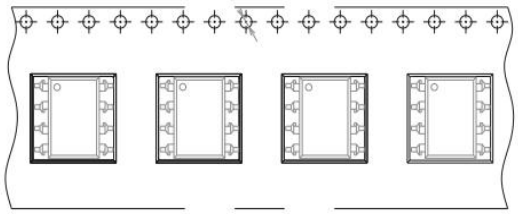
Y = 表示1位年份代码Denotes 1 digit Year code

WW = 表示2位周别代码Denotes 2 digit Week code

V = 表示VDE标识(客户指定镭射字符才加"V")
VDE (Only add "V" to laser characters specified by the customer)

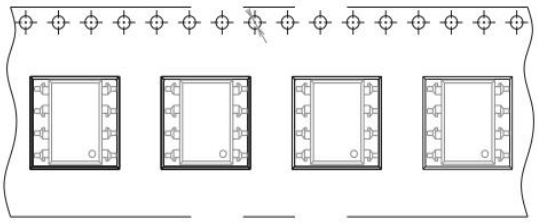
11.料带和卷轴包装规格 Tape & Reel Packing Specifications

• 选择TA Option TA



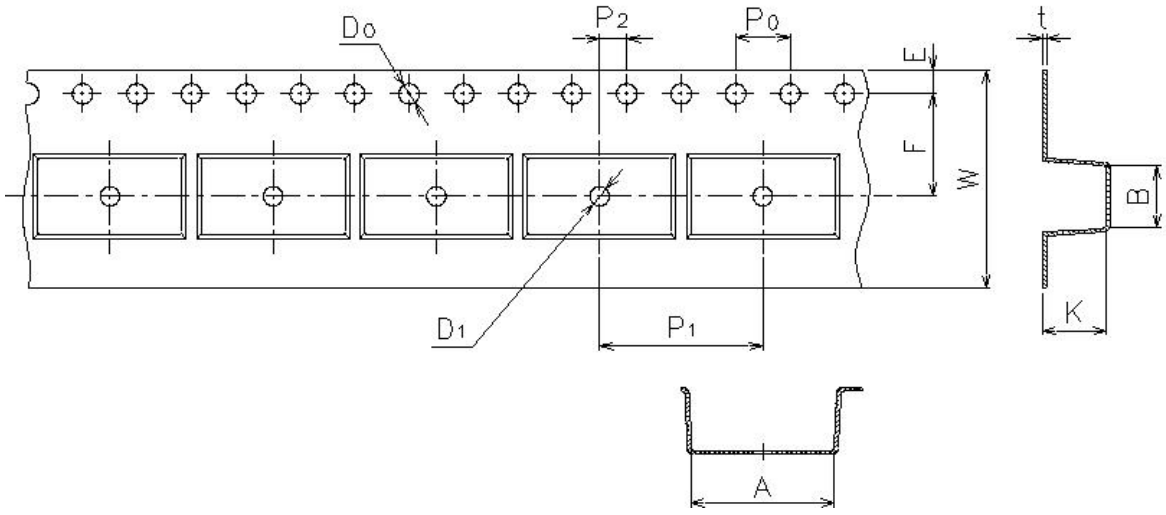
卷轴进给方向 Direction of feed from reel

• 选择TB Option TB



卷轴进给方向 Direction of feed from reel

料带尺寸Material belt size



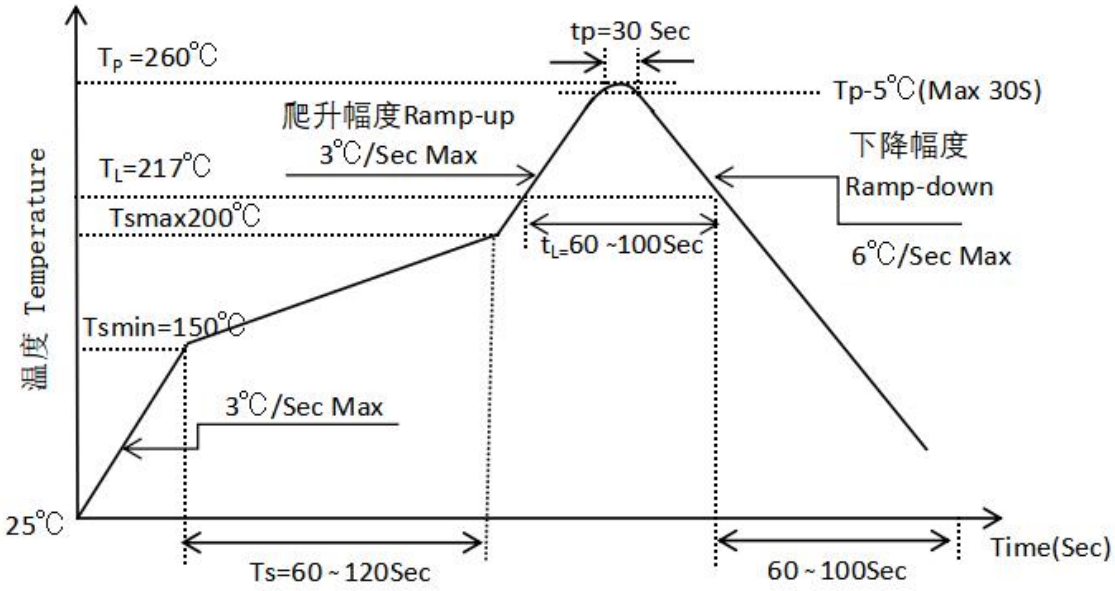
尺寸编号 Dimension No.	A0	B	D0	D1	E	F
尺寸(mm) Dimension(mm) S1	10.4±0.1	10.0±0.1	1.5+0.1/-0	1.50±0.25	1.75±0.1	7.5±0.1
尺寸编号 Dimension No.	P0	P1	P2	t	W	K
尺寸(mm) Dimension(mm) S1	4.0±0.1	12.0±0.1	2.0±0.05	0.4±0.05	16.0±0.3	4.5±0.1

12.焊接温度曲线 Temperature Profile Of Soldering

• 回流焊温度曲线 Reflow soldering

建议在下面所示的温度和时间分布条件下, 进行一次回流焊作业, 不得超过三次

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

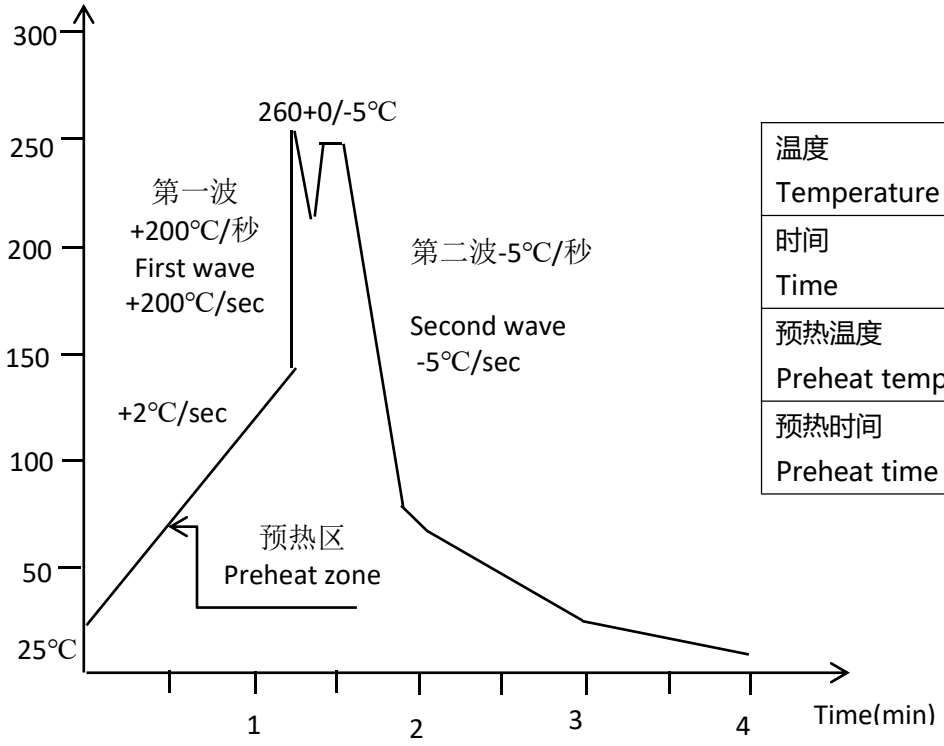


项目 Item	符号 Symbol	最小值 Min.	最大值 Max.	单位 Unit
预热温度 Preheat Temperature	T_s	150	200	℃
预热时间 Preheat Time	ts	60	120	s
升温速率 Ramp-Up Rate (T_L to T_P)	-	-	3	℃/s
液相线温度 Liquidus Temperature	T_L	217		℃
高于液相线温度(T_L)的时间 Time above Liquidus Temperature T_L	t_L	60	100	s
峰值温度 Peak Temperature	T_P	-	260	℃
T_c 在(T_P-5)和 T_P之间的时间 Time During Which T_c Is Between (T_P-5) and T_P	t_p	-	30	s
降温速率 Ramp-down Rate(T_P to T_L)	-	-	6	℃/s

• 波峰焊温度曲线 Wave Soldering

温度条件下, 建议一次焊接

One time soldering is recommended within the condition of temperature



温度 Temperature	260℃+0/-5℃
时间 Time	10秒 10S
预热温度 Preheat temperature	25至140℃ 25 to 140℃
预热时间 Preheat time	30至80秒 30 to 80 S